SIM Card Interface Filter and ESD Protection

Small Signal Discretes



Never stop thinking

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BGF106C

Features

- · ESD protection circuit and interface filter for SIM cards
- ESD protection according to IEC61000-4-2 for ± 15 kV contact discharge on external IOs
- Wafer level package with SnAgCu solder balls
- 400 μm solder ball pitch
- RoHS and WEEE compliant package



WLP-8-11-N-3D



Description

BGF106C is an ESD protection circuit and filtering interface for SIM cards. All external IOs are protected against ESD pulses of \pm 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green lead-free and halogen-free package with a size of only 1.2 mm x 1.2 mm and a total height of 0.6 mm

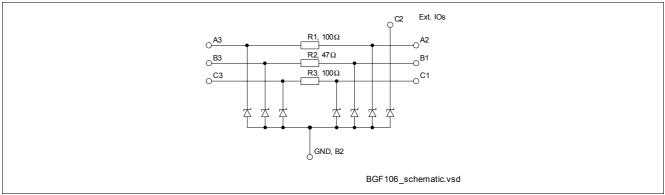


Figure 1 Schematic

Туре	Package	Marking	Chip
BGF106C	WLP-8-11	6C	N0727



Table 1 Maximum Ratings

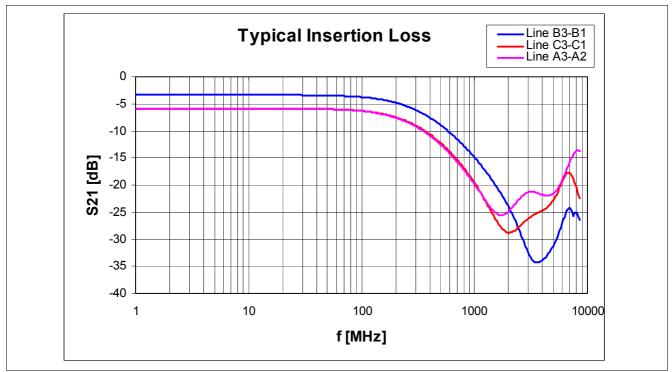
Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.	1	Test Condition
Voltage at all pins to GND	VP	0	-	5.5	V	_
Operating temperature range	T _{OP}	-40	_	+85	°C	_
Storage temperature range	T _{STG}	-65	-	+150	°C	_
Summed up input power for all pins	$P_{\rm in}$	-	_	60	mW	<i>T</i> _S < 70 °C
Electrostatic discharge according to IEC610	00-4-2					
Contact discharge at internal pins A3, B3, C3 to any other pin	V _{ESD}	-2	-	2	kV	-
Contact discharge at external pins A2, B1, C1, C2 to GND	V _{ESD}	-15	-	15	kV	-

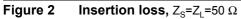
Table 2 Electrical Characteristics¹⁾

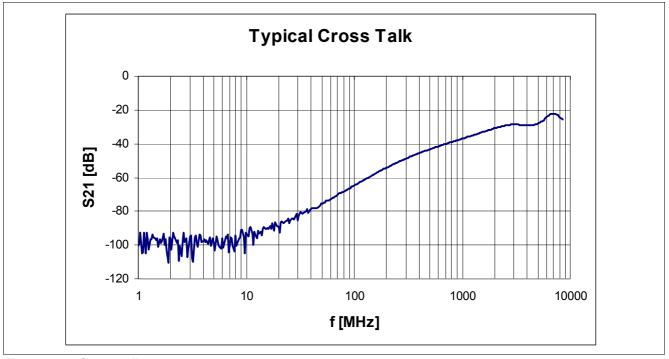
Symbol	Values			Unit	Note /
	Min.	Тур.	Max.	1	Test Condition
<i>R</i> _{1,3}	80	100	120	Ω	-
<i>R</i> ₂	37.6	47	56.4	Ω	-
I _R	_	1	100	nA	<i>V</i> = 3 V
	-	2	1000	nA	V = 5 V
V _(BR)	6.5	7.8	-	V	I _(BR) = 1 mA
CT	_	16.5	20	pF	<i>V</i> = 0 V
	$ \begin{array}{c} R_{1,3} \\ R_2 \\ I_R \\ V_{(BR)} \end{array} $	$\begin{tabular}{ c c c c c } \hline Min. \\ \hline $Min.$ \\ \hline $Min.$ \\ 80 \\ $R_{1,3}$ \\ 80 \\ \hline R_{2} \\ 37.6 \\ \hline I_{R} \\ $-$ \\ $-$ \\ \hline $V_{(BR)}$ \\ 6.5 \\ \hline \end{tabular}$	$\begin{tabular}{ c c c c c } \hline Min. $Typ.$ \\ \hline Min. $Typ.$ \\ \hline Min. $Typ.$ \\ \hline $R_{1,3}$ $80 100 \\ \hline R_2 $37.6 47 \\ \hline I_R $-$ 1 \\ -$ 2 \\ \hline $V_{(BR)}$ $6.5 7.8 \\ \hline \end{tabular}$	Min. Typ. Max. $R_{1,3}$ 80 100 120 R_2 37.6 47 56.4 I_R - 1 100 $-$ 2 1000 $V_{(BR)}$ 6.5 7.8 -	Min. Typ. Max. $R_{1,3}$ 80 100 120 Ω R_2 37.6 47 56.4 Ω I_R - 1 100 nA $-$ 2 1000 nA $V_{(BR)}$ 6.5 7.8 - V

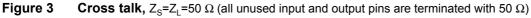
1) at $T_{A} = 25 \,^{\circ}\text{C}$





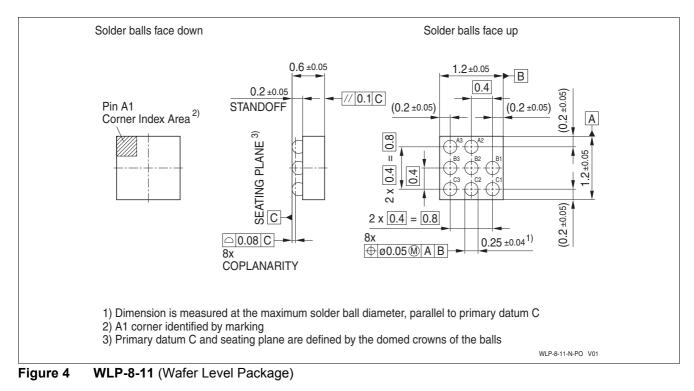




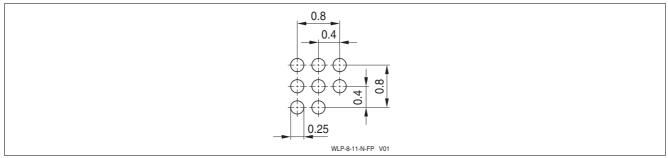


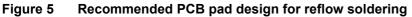


Package Outlines



Footprint





Таре

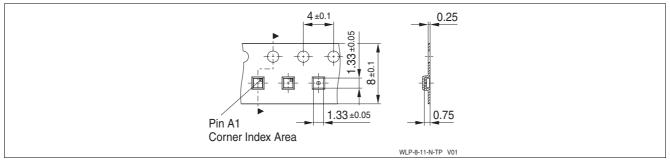


Figure 6 Tape for BGF106C / WLP-8-11

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